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Claims

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- 1. A high power light emitting diode package comprising:
- a main body;
- at least two lead terminals fixed to the main body; and
- at least two heat sinks of electrically and thermally conductive materials, the heat sinks being separated from each other and fixed to the main body.
 - 2. The package of claim 1, wherein each of the at least two heat sinks has a reflective surface extended from an upper surface thereof.
 - 3. The package of claim 1, wherein the at least two heat sinks are a pair.
 - 4. The package of claim 3, further comprising:
- at least one light emitting diode die mounted on upper surfaces of the at least two heat sinks, the die being directly and electrically connected to the heat sinks through a surface of the die.
 - 5. The package of claim 4, further comprising:

bonding wires electrically connecting the at least two lead terminals, the at least 20 two heat sinks and the at least one light emitting diode die.

- 6. The package of claim 4, further comprising:
- a lens attached to the main body, the lens enclosing the at least one light emitting diode die.
- 7. The package of claim 6, wherein the lens includes an optically transparent material which is directly contacted with the at least one light emitting diode die.
 - 8. The package of claim 4, further comprising:
- a fluorescent material converting the wavelength of light emitted from the at least one light emitting diode die.

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9. The package of claim 1, further comprising:

light emitting diode dies mounted on the respective heat sinks, the light emitting diode dies emitting different wavelengths of light.

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and

10. The package of claim 9, wherein the at least two lead terminals include: lead terminals electrically connected to the at least two heat sinks respectively;

a common lead terminal electrically connected to all of the at least two heat sinks.

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- 11. The package of claim 10, further comprising: an additional heat sink; and
- a zener diode mounted on the additional heat sink.
- 12. The package of claim 9, wherein the light emitting diode dies include light emitting diode dies emitting a first wavelength of light, a second wavelength of light and a third wavelength of light, respectively.
- 13. The package of claim 13, wherein the first wavelength, the second wavelength and the third wavelength are red wavelength, green wavelength and blue wavelength, respectively.
 - 14. A light emitting diode system comprising:

the light emitting diode package according to claim 10 or claim 11; and

a controller for controlling the electric power supplied to the light emitting diode package,

wherein the controller controls the amount of the current supplied to the respective heat sinks.

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